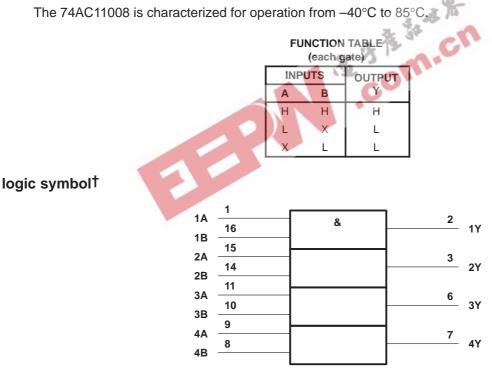
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 Flow-Through Architecture Optimizes PCB Layout 	D, N, OR PW PACKAGE (TOP VIEW)				
 Center-Pin V_{CC} and GND Configurations Minimize High-Speed Switching Noise 					
 EPIC[™] (Enhanced-Performance Implanted CMOS) 1-µm Process 	1Y 2 15 2A 2Y 3 14 2B GND 4 13 Vcc				
 500-mA Typical Latch-Up Immunity at 125°C 	GND 4 13 V _{CC} GND 5 12 V _{CC} 3Y 6 11 3A				
 Package Options Include Plastic Small-Outline (D) and Thin Shrink Small-Outline (PW) Packages, and 	4Y [7 10] 3B 4B [8 9] 4A				
Standard Plastic 300-mil DIPs (N)					

description

This device contains four independent 2-input AND gates. It performs the Boolean function $Y = A \bullet B$ or $Y = \overline{A} + \overline{B}$ in positive logic.



[†] This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.



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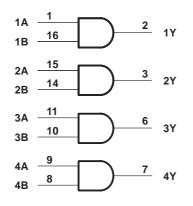
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logic diagram (positive logic)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)[†]

Storage temperature range, Tstg

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

2. The maximum package power dissipation is calculated using a junction temperature of 150°C and a board trace length of 750 mils, except for the N package, which has a trace length of zero.



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			MIN	NOM	MAX	UNI	
VCC	Supply voltage		3	5	5.5	V	
		V _{CC} = 3 V	2.1				
VIH	High-level input voltage	V _{CC} = 4.5 V	3.15			V	
		V _{CC} = 5.5 V	3.85				
		$V_{CC} = 3 V$			0.9		
VIL	Low-level input voltage	$V_{CC} = 4.5 V$			1.35	V	
		V _{CC} = 5.5 V			1.65		
VI	Input voltage	-	0		VCC	V	
Vo	Output voltage		0		VCC	V	
		V _{CC} = 3 V			-4		
ЮН	High-level output current	V _{CC} = 4.5 V			-24	mA	
		V _{CC} = 5.5 V			-24		
		V _{CC} = 3 V			12		
IOL	Low-level output current	$V_{CC} = 4.5 V$			24	mA	
		V _{CC} = 5.5 V			24		
$\Delta t / \Delta v$	Input transition rise or fall rate	a 34 🔥	0		10	ns/\	
TA	Operating free-air temperature	23	-40		85	°C	

recommended operating conditions

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	Vac	T _A = 25°C			MIN	MAX	UNIT
PARAMETER	TEST CONDITIONS	Vcc	MIN	TYP	MAX		WAA	UNIT
		3 V	2.9			2.9		
	I _{OH} = -50 μA	4.5 V	4.4			4.4		
		5.5 V	5.4			5.4		
VOH	$I_{OH} = -4 \text{ mA}$	3 V	2.58			2.48		V
		4.5 V	3.94			3.8		
	$I_{OH} = -24 \text{ mA}$	5.5 V	4.94			4.8		
	$I_{OH} = -75 \text{ mA}^{\dagger}$	5.5 V				3.85		
		3 V			0.1		0.1	
	I _{OL} = 50 μA	4.5 V			0.1		0.1	
					0.1		0.1	
VOL	I _{OL} = 12 mA	3 V			0.36		0.44	V
	lot = 24 mA	4.5 V			0.36		0.44	
	$I_{OL} = 24 \text{ mA}$	5.5 V			0.36		0.44	
	$I_{OL} = 75 \text{ mA}^{\dagger}$	5.5 V					1.65	
lj	$V_I = V_{CC}$ or GND	5.5 V			±0.1		±1	μA
Icc	$V_{I} = V_{CC} \text{ or } GND, \qquad I_{O} = 0$	5.5 V			4		40	μA
Ci	$V_I = V_{CC}$ or GND	5 V		3.5				pF

[†] Not more than one output should be tested at a time, and the duration of the test should not exceed 10 ms.



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switching characteristics over recommended operating free-air temperature range, V_{CC} = 3.3 V \pm 0.3 V (unless otherwise noted) (see Figure 1)

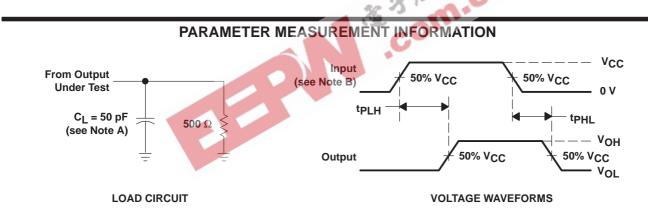
PARAMETER	FROM	ТО	T _A = 25°C		MIN	MINI	MAX	UNIT
PARAMETER	(INPUT)	(OUTPUT)	MIN	TYP	MAX	IVIIIN	IVIAA	UNIT
^t PLH	A or B	Y	1.5	6.3	9	1.5	10.2	20
^t PHL	AUB		1.5	5.6	7.8	1.5	8.6	ns

switching characteristics over recommended operating free-air temperature range, V_{CC} = 5 V \pm 0.5 V (unless otherwise noted) (see Figure 1)

PARAMETER	FROM	ТО	T _A = 25°C		MIN	МАХ	UNIT	
PARAMETER	(INPUT)	(OUTPUT)	MIN	TYP	MAX	IVIIIN	IVIAA	UNIT
^t PLH	A or B	V	1.5	4.3	6.2	1.5	6.9	
^t PHL	AUB	T	1.5	5.6	5.9	1.5	6.5	ns

operating characteristics, $V_{CC} = 5 V$, $T_A = 25^{\circ}C$

PARAMETER			TEST CONDITIONS		
C _{pd}	Power dissipation capacitance per gate	CL = 50 pF,	f = 1 MHz	29	pF



NOTES: A. CL includes probe and jig capacitance.

B. Input pulses are supplied by generators having the following characteristics: PRR \leq 1 MHz, Z_O = 50 Ω , t_f = 3 ns, t_f = 3 ns.

C. The outputs are measured one at a time with one input transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms



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